

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
 Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	<b>Company Unique ID</b> 00-489-5751	<b>Unique ID Authority</b> Dun & Bradstreet	<b>Response Date*</b> Sat, Aug 24, 2013 02:56 AM
<b>Contact Name *</b> David Lancaster	<b>Title - Contact</b> Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	<b>Title - Representative</b> Product Ecology	<b>Phone - Representative *</b> 801-562-7455	<b>Email - Representative *</b> david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FOD4118S	FOD4118S	DIPB-6			INTERNAL PENANG	0.537109	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	C	30 seconds	3

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive</b> 2011/65/EU	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b>	<b>1 - Item(s) does not contain RoHS restricted substances per the definition above</b>	<b>Supplier Acceptance * Accepted</b>
<p><b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p>		
<p>Exemption List Version EL-2011/534/EU None</p>		

#### Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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# Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DIPB-6

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	4.043	Supplier		Gallium Arsenide	0.283	1303-00-0	527
			Supplier		Silicon	3.760	7440-21-3	7000
Coupling Gel	Other Organic Materials	1.830	Supplier		Dimethyl Siloxane	0.888	68083-19-2	1653
			Supplier		Silane	0.307	2530-85-0	572
			Supplier		Titanium Dioxide	0.635	13463-67-7	1182
Die Attach	Other Organic Materials	1.665	Supplier		Acrylic Resin	0.415	54208-63-8	773
			Supplier		Silver	1.250	7440-22-4	2327
Encapsulation	Thermoplastics	414.400	B	Antimony/Antimony Compounds	Antimony Trioxide	12.400	1309-64-4	23087
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	16.600	6386-73-8	30906
			Supplier		Carbon Black	4.150	1333-86-4	7727
			Supplier		Epoxy Resin	95.400	29690-82-2	177617
			Supplier		Silica, vitreous	285.850	60676-86-0	532201
Lead Frame	Copper & its alloys	108.322	Supplier		Copper	105.000	7440-50-8	195491
			Supplier		Iron	2.480	7439-89-6	4617
			Supplier		Phosphorus	0.032	7723-14-0	60
			Supplier		Silver	0.680	7440-22-4	1266
			Supplier		Zinc	0.130	7440-66-6	242
Plating	Other Nonferrous metals & alloys	6.700	Supplier		Tin	6.700	7440-31-5	12474
Wire Bond	Precious metals	0.149	Supplier		Gold	0.149	7440-57-5	277